

May 2008

74VHCT74A Dual D-Type Flip-Flop with Preset and Clear

Features

- n High speed: $f_{MAX} = 160MHz$ (Typ.) at $T_A = 25^{\circ}C$
- $\rm n~$ High noise immunity: $V_{IH}=2.0V,~V_{IL}=0.8V$
- Power down protection is provided on all inputs and outputs
- $\rm n~$ Low power dissipation: $I_{CC}=2\mu A$ (Max.) at $T_A=25^{\circ}C$
- n Pin and function compatible with 74HCT74

General Description

The VHCT74A is an advanced high speed CMOS Dual D-Type Flip-Flop fabricated with silicon gate CMOS technology. It achieves the high speed operation similar to equivalent Bipolar Schottky TTL while maintaining the CMOS low power dissipation. The signal level applied to the D INPUT is transferred to the Q OUTPUT during the positive going transition of the CK pulse. CLR and PR are independent of the CK and are accomplished by setting the appropriate input LOW.

Protection circuits ensure that 0V to 7V can be applied to the input pins without regard to the supply voltage and to the output pins with $V_{CC} = 0V$. These circuits prevent device destruction due to mismatched supply and input/ output voltages. This device can be used to interface 3V to 5V systems and two supply systems such as battery backup.

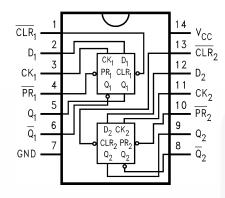
Ordering Information

Order Number	Package Number	Package Description
74VHCT74AM	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
74VHCT74ASJ	M14D	14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74VHCT74AMTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.

All packages are lead free per JEDEC: J-STD-020B standard.

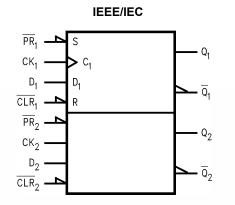
Connection Diagram



Pin Description

Pin Names	Description			
D ₁ , D ₂	Data Inputs			
CK ₁ , CK ₂	Clock Pulse Inputs			
CLR ₁ , CLR ₂	Direct Clear Inputs			
$\overline{PR}_1, \overline{PR}_2$	Direct Preset Inputs			
$Q_1, \overline{Q}_1, Q_2, \overline{Q}_2$	Outputs			

Logic Symbol



Truth Table

	Inputs Outputs					
CLR	PR	D	СК	Q	Q	Function
L	Н	Х	Х	L	Н	Clear
Н	L	Х	Х	Н	L	Preset
L	L	Х	Х	Н	Н	
Н	Н	L	~	L	Н	
Н	Н	Н	~	Н	L	
Н	Н	Х	~	Q _n	Q _n	No Change

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Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
V _{CC}	Supply Voltage	-0.5V to +7.0V
V _{IN}	DC Input Voltage	–0.5V to +7.0V
V _{OUT}	DC Output Voltage	
	Note 1	–0.5V to V _{CC} + 0.5V
	Note 2	–0.5V to 7.0V
I _{IK}	Input Diode Current	–20mA
I _{ОК}	Output Diode Current ⁽³⁾	±20mA
I _{OUT}	DC Output Current	±25mA
I _{CC}	DC V _{CC} /GND Current	±50mA
T _{STG}	Storage Temperature	–65°C to +150°C
Т	Lead Temperature (Soldering, 10 seconds)	260°C

Recommended Operating Conditions⁽⁴⁾

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating
V _{CC}	Supply Voltage	4.5V to +5.5V
V _{IN}	Input Voltage	0V to +5.5V
V _{OUT}	Output Voltage	
	Note 1	0V to V _{CC}
	Note 2	0V to 5.5V
T _{OPR}	Operating Temperature	–40°C to +85°C
t _r , t _f	Input Rise and Fall Time	
	$V_{CC} = 5.0V \pm 0.5V$	0ns/V ~ 20ns/V

Notes:

1. HIGH or LOW state. I_{OUT} absolute maximum rating must be observed.

2. $V_{CC} = 0V$.

- 3. $V_{OUT} < GND$, $V_{OUT} > V_{CC}$ (Outputs Active).
- 4. Unused inputs must be held HIGH or LOW. They may not float.

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DC Electrical Characteristics

					т	A = 25°	С		–40°C 85°C	
Symbol	Parameter	$V_{CC}(V)$	Con	ditions	Min.	Тур.	Max.	Min.	Max.	Units
V _{IH}	HIGH Level Input	4.5			2.0			2.0		V
	Voltage	5.5			2.0			2.0		
V _{IL}	LOW Level Input	4.5					0.8		0.8	V
	Voltage	5.5					0.8		0.8	
V _{OH}	HIGH Level Output	4.5		$I_{OH} = -50 \mu A$	4.40	4.50		4.40		V
	Voltage	4.5	or V _{IL}	$I_{OH} = -8mA$	3.94			3.80		
V _{OL}	LOW Level Output	4.5		$I_{OL} = 50 \mu A$		0.0	0.1		0.1	V
	Voltage	4.5	or V _{IL}	$I_{OL} = 8mA$			0.36		0.44	
I _{IN}	Input Leakage Current	0–5.5	V _{IN} = 5.5V	or GND			±0.1		±1.0	μA
I _{CC}	Quiescent Supply Current	5.5	$V_{IN} = V_{CC}$	or GND			2.0		20.0	μA
I _{CCT}	Maximum I _{CC} /Input	5.5	V _{IN} = 3.4V Inputs = V	, Other _{CC} or GND			1.35		1.50	mA
I _{OFF}	Output Leakage Current (Power Down State)	0.0	V _{OUT} = 5.8	5V			+0.5		+5.0	μA

AC Electrical Characteristics

				т		с		-40°C 85°C	
Symbol	Parameter	V _{CC} (V) ⁽⁵⁾	Conditions	Min.	Тур.	Max.	Min.	Max.	Units
f _{MAX}	Maximum Clock	5.0	$C_L = 15 p F$	100	160		80		MHz
	Frequency	5.0	$C_L = 50 pF$	80	140		65		
t _{PLH} , t _{PHL}		5.0	$C_L = 15 pF$		5.8	7.8	1.0	9.0	ns
	Time (CK-Q, Q)	5.0	$C_L = 50 pF$		6.3	8.8	1.0	10.0	
t _{PLH} , t _{PHL}	Propagation Delay	5.0	$C_L = 15 pF$		7.6	10.4	1.0	12.0	ns
	Time (CLR, PR-Q, Q)	5.0	$C_L = 50 pF$		8.1	11.4	1.0	13.0	
C _{IN}	Input Capacitance		$V_{CC} = Open$		4	10		10	pF
C _{PD}	Power Dissipation Capacitance		(6)		24				pF

Notes:

5. V_{CC} is 5.0 \pm 0.5V

6. C_{PD} is defined as the value of internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC} (Opr.) = $C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC} / 2$ (per flip-flop).

			T _A =	25°C	T _A = -40°C to +85°C	
Symbol	Parameter	V _{CC} (V)	Тур.		aranteed nimum	Units
t _W (L), t _W (H)	Minimum Pulse Width (CK)	5.0 ± 0.5		5.0	5.0	ns
t _W (L)	Minimum Pulse Width (CLR, PR)	5.0 ± 0.5		5.0	5.0	ns
t _S	Minimum Setup Time	5.0 ± 0.5		5.0	5.0	ns
t _H	Minimum Hold Time	5.0 ± 0.5		0	0	ns
t _{REM}	Minimum Removal Time (CLR, PR)	5.0 ± 0.5		3.5	3.5	ns

Physical Dimensions

Figure 1. 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow

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Figure 2. 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide

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Figure 3. 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

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